

Title (en)
DISSIPATING HEAT FROM AN ELECTRONIC ASSEMBLY USING FORCED CONVECTION, AND METHOD FOR DISSIPATING HEAT FROM AN ELECTRONIC ASSEMBLY

Title (de)
ENTWÄRMUNG EINER ELEKTRONISCHEN BAUGRUPPE MITTELS FORCIERTER KONVEKTION, SOWIE VERFAHREN ZUM ENTWÄRMEN EINER ELEKTRONISCHEN BAUGRUPPE

Title (fr)
DISSIPATION DE LA CHALEUR D'UN BLOC ÉLECTRONIQUE PAR CONVECTION FORCÉE, ET PROCÉDÉ POUR DISSIPER LA CHALEUR D'UN BLOC ÉLECTRONIQUE

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Application
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Abstract (en)
[origin: WO2020160978A1] The invention relates to an electronic assembly (1) comprising: - a printed circuit board (2) which is designed with a first populating side (3) and a second populating side (4), - at least one first heat sink (5) which is arranged on the first populating side (3), - multiple electronic components (6), a plurality of which are arranged on the second populating side (4) of the printed circuit board (2), - at least one first non-current-conducting via (7) in the printed circuit board (2), said via being used to transport the thermal energy generated by an electronic component (6) from the second populating side (4) to the first populating side (3), and - a convection unit (8) for generating a forced convection (9) solely on the first populating side (3), wherein the thermal energy can be transported away from the printed circuit board (2) of the electronic assembly (1) by means of the forced convection so that heat can be dissipated from the electronic assembly (1). The invention additionally relates to a method for dissipating heat from an electronic assembly (1).

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